

1 ABSTRACT OF THE DISCLOSURE

 A method of mounting a semiconductor device
having bumps on a board having pads so that each of
the bumps is joined to a corresponding one of the pads
5 is provided. Adhesive to be hardened by heat is
provided between the semiconductor device and the
board. The method includes the steps of pressing the
bumps of the semiconductor device on the pads of the
board, and heating a portion in which each of the
10 bumps and a corresponding one of the pads are in
contact with each other. A pressure of the bumps to
the pads reaches a predetermined value before a
temperature of the adhesive to which heat is supplied
in the above step reaches a temperature at which the
15 adhesive is hardened.

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